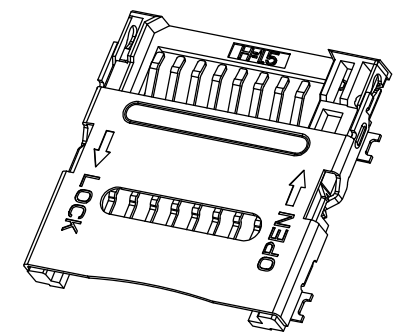
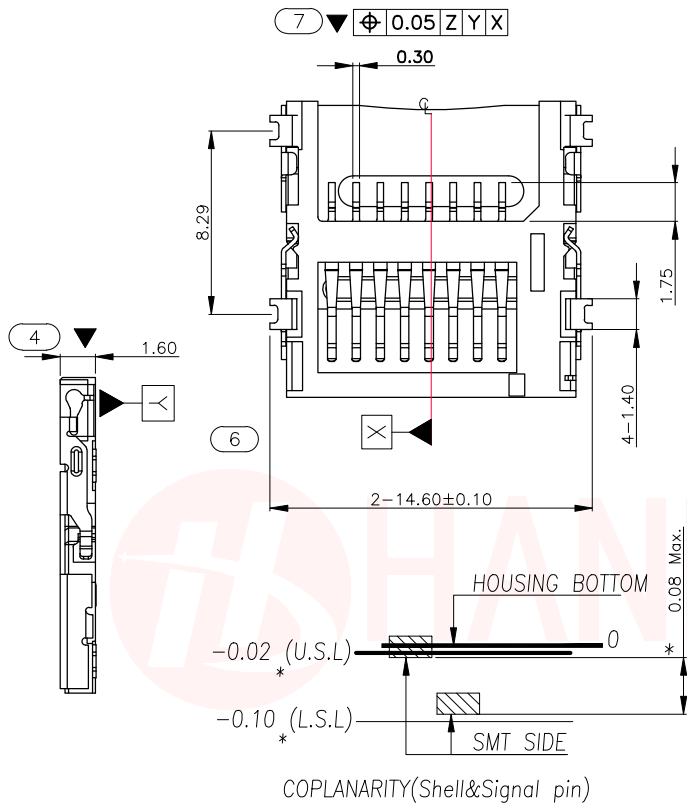
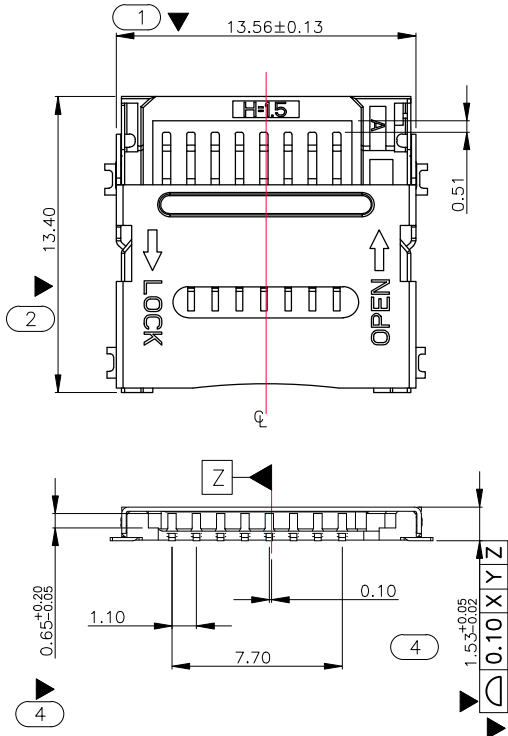
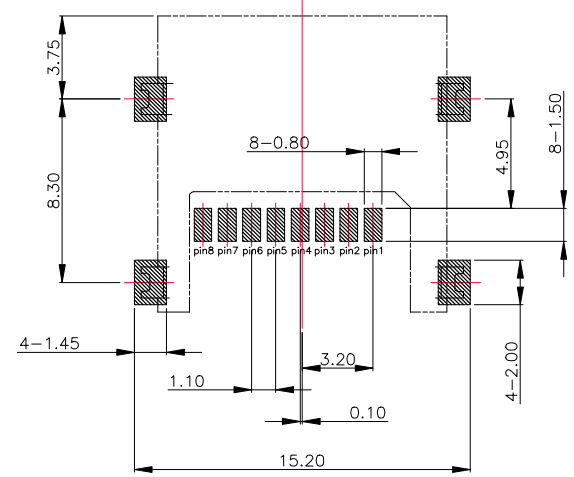
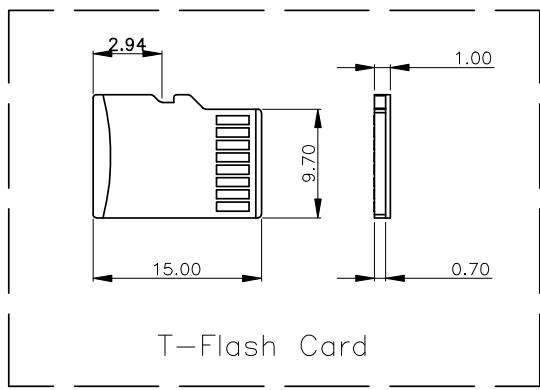




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



NOTE:
 1.FINISH:
 1-1.CONTACT: AU 1U" PLATING ON CONTACT AREA, 100~200U" SN PLATING ON SOLDER TAILS, 50U" NICKEL UNDERPLATING VOER ALL;
 1-2.SHELL: NO PLATING;
 2.PRODUCT SPECIFICATIONS:
 2-1.VOLTAGE RATING: 100V
 2-2.CURRENT RATING: 0.5A
 2-3.INSULATION RESISTANCE: 1000 MEG.OHM MIN
 2-4.CONTACT RESISTANCE: 100 MILL.OHM MAX
 2-5.OPERATION TEMPERATURE: -20° TO +85°



RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

PIN NO.	NAME	YTYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: X :±0.5 X.X :±0.20 X.XX :±0.10
 ANGLES: X :±2° X.X :±1°

TITLE		MICRO SD CARD HINGED H16	
DWN	xiong	TF-014-H16	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1
		REV: A4	

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